



STEIF POWER  
TECHNOLOGY

100V P-Channel MOSFETs

**SPP0959**

## General Description

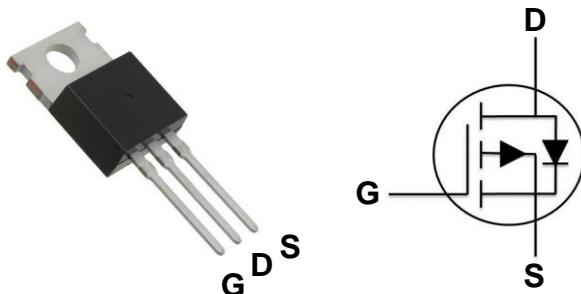
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
-100V	45mΩ	-35A

## Features

- -100V,-35A, RDS(ON) 45mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

## TO220 Pin Configuration



## Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	-100	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	-35	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	-22	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-140	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	180	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	-60	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	114	W
	Power Dissipation – Derate above 25°C	0.91	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C



## Applications

- Networking
- Load Switch
- LED applications

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	1.1	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-100	---	---	V
$I_{DS}$	Drain-Source Leakage Current	$V_{DS}=-100\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=85\text{ }^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$ , $I_D=-15\text{A}$	---	36	45	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-10\text{A}$	---	40	55	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = -250\mu\text{A}$	-1.2	---	-2.5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-5\text{A}$	---	22	---	S

**Dynamic and switching Characteristics**

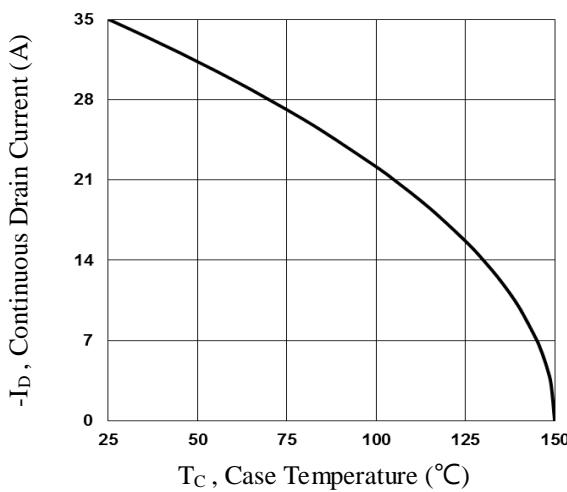
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=-50\text{V}$ , $V_{GS}=-10\text{V}$ , $I_D=-10\text{A}$	---	98	150	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	16.2	30	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	13.8	26	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=-50\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=25\Omega$ $I_D=-5\text{A}$	---	58	105	ns
$T_r$	Rise Time <sup>3,4</sup>		---	24	50	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	215	450	
$T_f$	Fall Time <sup>3,4</sup>		---	94	180	
$C_{iss}$	Input Capacitance	$V_{DS}=-25\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	6315	9000	pF
$C_{oss}$	Output Capacitance		---	220	330	
$C_{rss}$	Reverse Transfer Capacitance		---	50	100	

**Drain-Source Diode Characteristics and Maximum Ratings**

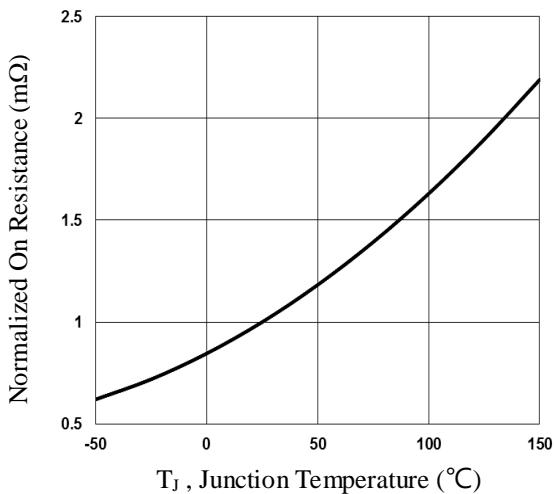
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-35	A
			---	---	-70	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	-1	V

Note :

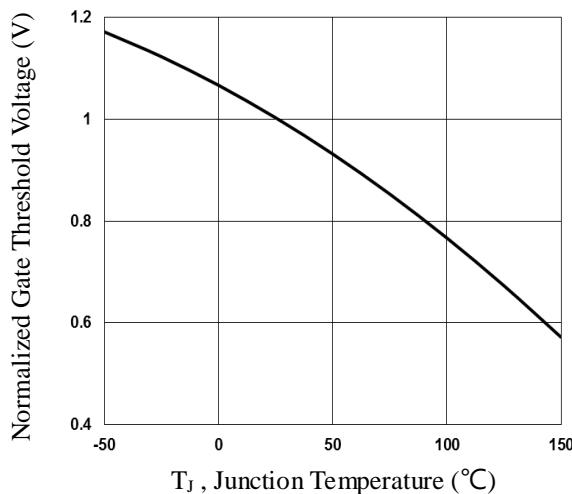
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-50\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-60\text{A}$ , Starting  $T_J=25\text{ }^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



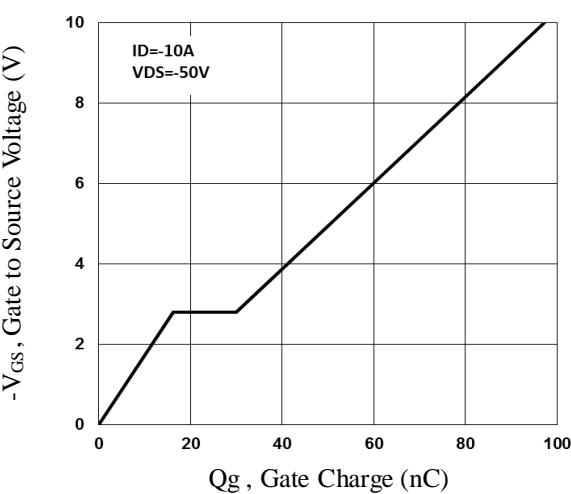
**Fig.1 Continuous Drain Current vs. T<sub>C</sub>**



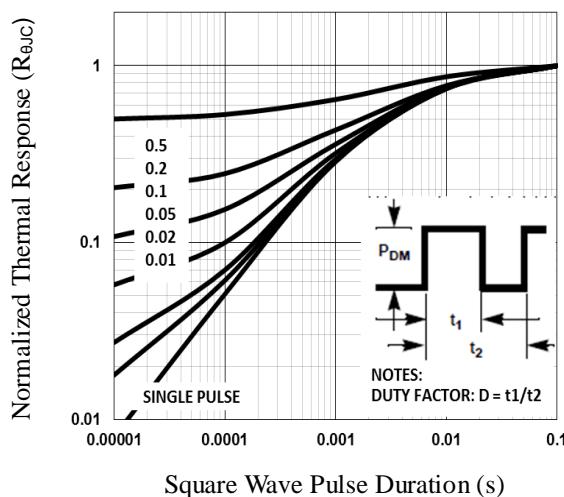
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



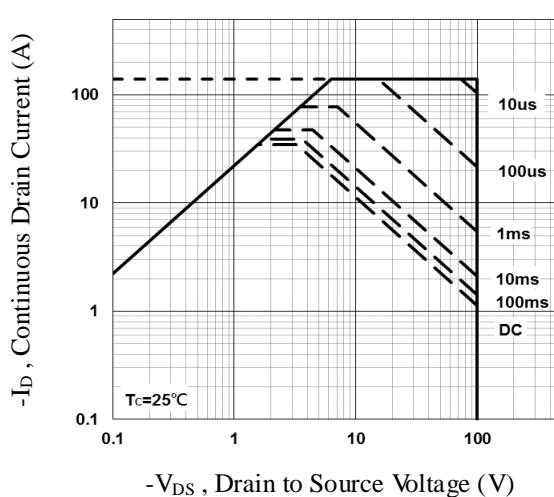
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>**



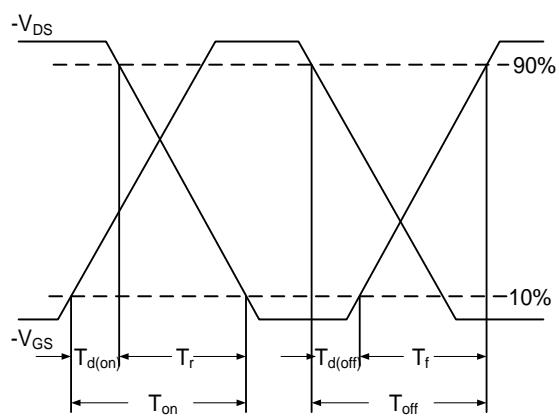
**Fig.4 Gate Charge Waveform**



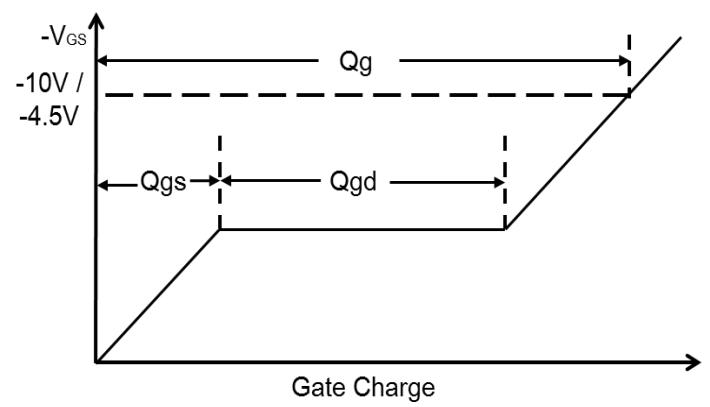
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

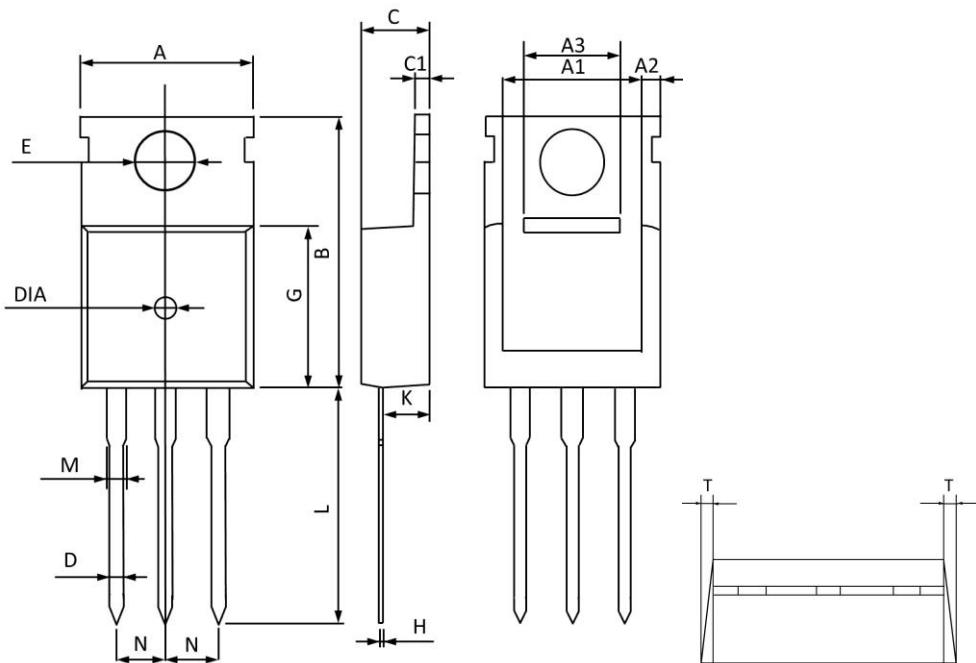


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

## TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.